March 18, 2026
Fuji Corporation
Fasford Technology Co., Ltd.

FUJI Group's Fasford Technology to Unveil Next-Generation Die Bonder "XERDIA" at SEMICON CHINA 2026 for the First Time in the World

Fasford Technology Co., Ltd. (Head Office: Minami-Alps City, Yamanashi Prefecture; President & CEO: Hiroyuki Ao; hereinafter "Fasford Technology"), a group company of Fuji Corporation (Head Office: Chiryu City, Aichi Prefecture; President & CEO: Joji Isozumi; hereinafter "FUJI"), which develops, manufactures, and sells semiconductor manufacturing equipment, will unveil its next-generation flagship die bonder, **"XERDIA**," for the first time in the world at **SEMICON CHINA 2026, to be held in Shanghai from March 25 (Wednesday) to March 27 (Friday), 2026**.

XERDIA

XERDIA

Planned Exhibit Models at SEMICON CHINA 2026

A die bonder is a semiconductor backend manufacturing system that bonds semiconductor chips ("dies"), containing integrated electronic circuits, onto substrates. In recent years, as semiconductor devices have continued to advance in functionality and memory capacity, the importance of advanced packaging technologies that enable the high-density integration of multiple dies has been increasing. In such high-density packaging, even slight die misalignment can significantly impact device reliability, making high-precision die bonding technology essential. Furthermore, driven by the rapid expansion of data processing demand—particularly from generative AI—data volumes are growing explosively. Along with the widespread adoption of data centers and AI-related equipment that support this growth, demand for semiconductors, especially memory devices, is steadily increasing. As a result, semiconductor manufacturing processes are now required to achieve not only higher precision, but also greater productivity.

To address these market needs, Fasford Technology has developed “XERDIA.”

XERDIA is a next-generation model that inherits the design philosophy of the conventional DB830/DB850 series, while undergoing a comprehensive redesign of its entire platform—including the **equipment frame, core modules, and the integrated hardware and software control systems**. Through this complete renewal, XERDIA achieves a significant leap in performance, **improving bonding accuracy from 5 μm to 3 μm (*), and dramatically increasing productivity (*) from UPH 4,000 to UPH 5,500**.

In addition, leveraging the ease of use matured through the DB series, XERDIA delivers both advanced functionality and a highly user-friendly operating experience.

*Based on the Fasford Technology standard configuration.

■ Four Core Development Concepts

In developing a next-generation die bonder that responds to these market needs, Fasford Technology set out to **establish a new industry benchmark for next-generation mass production equipment**, and developed “XERDIA” based on the following four development concepts.

1. Unstoppable Productivity

By reducing vibration by 50% compared with conventional models through a high-rigidity system frame, and by introducing newly redesigned core modules, XERDIA further **enhances the industry-proven high operational uptime** of previous models.

2. Effortless Operation

A new control platform significantly improves operability, while features such as automatic tool change and universalized window clamper enhance setup efficiency and serviceability by **up to 34%**.

3. Designed for value

By maximizing the use of existing DB series assets, including tools and process recipes, XERDIA achieves **seamless use of your existing assets while ensuring a smooth transition from existing systems**.

4. Green by design

XERDIA reduces environmental impact by maximizing footprint productivity—achieving a 30% improvement compared to conventional models—and by enhancing energy efficiency through its new control platform.
As a result, power consumption during **standby operation has been reduced by 13%**, while the introduction of ECO Mode 2.0 further **cuts power consumption during idle operation by 26%**.

■ First Newly Developed Product Since Joining the FUJI Group

"XERDIA" is the **first piece of equipment developed entirely from the ground up since Fasford Technology became part of the FUJI Group** in 2018.

By incorporating linear motors manufactured by Fuji Linear Corporation, another FUJI Group company, and featuring equipment design created in collaboration with the FUJI design team, XERDIA represents the culmination of a new design philosophy that fully leverages the technological synergies of the FUJI Group.

■ Exhibition Information at SEMICON CHINA 2026

During SEMICON CHINA 2026, held from March 25 (Wednesday) to March 27 (Friday), 2026, Fasford Technology will present a reference exhibit of the in-development "XERDIA" system at the booth of its distributor in China, JIPAL Corporation (Hall N4 / Booth No. 4151).

Market feedback obtained through this exhibition will be reflected in future product development.

At the same time, FUJI will showcase a wide range of automation solutions at its own booth (Hall E4 / Booth No. 4342), including the "NXTR" SMT pick and place machine, which enables automated changeovers and component supply in the SMT process (*).

*Surface mount technology (SMT), the process of placing components onto PCB assembly

■ Future Plans

Product Commercialization Schedule

The official release of "XERDIA" is **scheduled for June 2026**.

Through this development, Fasford Technology aims to strengthen its capabilities in the advanced packaging field and create new market value. Fasford Technology will also continue to leverage the technological synergies of the FUJI Group to contribute to technological innovation in semiconductor manufacturing.

■ Company Profile

Fasford Technology

Company Name: Fasford Technology Co., Ltd.

Representative: Hiroyuki Ao, President & CEO

Head Office: 610-5 Shimoimasuwa, Minami-Alps City, Yamanashi 400-0212, Japan

Established: March 2015

Business Description: Design, manufacturing, sales, repair, and maintenance services of semiconductor manufacturing equipment

Capital: JPY 450.5 million

URL: https://www.fasford-tech.com/en/

FUJI

Company Name: Fuji Corporation

Representative: Joji Isozumi, President & CEO

Head Office: 19 Chausuyama, Yamamachi, Chiryu City, Aichi 472-8686, Japan

Established: April 1959

Business Description: Development, manufacturing, and sales of SMT pick and place machines and machine tools

Capital: JPY 5,878 million

URL: https://www.fuji.co.jp/en/

■ Contact Information for This Announcement

Fasford Technology Co., Ltd. Web Inquiry Form

https://www.fasford-tech.com/en/contact/